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Introduction

Motivation

DC-link voltage ~1500V is required for renewable energy applications.

- 2-level topology with 3.3kV devices:
 Large switching losses due to the high blocking voltage device.
- 3-level NPC topology with 1.2kV devices: Large number of devices and gate drives Bigger commutation inductance

Our Proposal

New 2.3kV devices for renewable energy systems.

- Advantages of 2-level topology with 2.3kV devices:
 - ✓ Smaller footprint size
 - ✓ Smaller number of gate drivers
 - ✓ Lower on-state losses
 - Lower commutation inductance







Technology of 2.3kV Si IGBT



- ◆ 2.3kV Si-IGBT device based on the 7th Gen technology
- Thinner drift layer
- Low on-state voltage and low conduction loss

Technologies of 7G IGBT

- Thinner drift layer
 - Reduce $V_{CE(sat)}$ and E_{off}
- More fine pattern of trench pitch
 Reduce V_{CE(sat)} and E_{off}
- Optimized Field-Stop layer
 - Secure breakdown voltage
 - Low leakage current at high temperature



Cross section view of Si-IGBT chip



Technology of 2.3kV SiC-MOSFET



Fuji 2^{nd} Gen SiC-MOSFET has 23% lower R_{on} than Fuji 1^{st} Gen SiC-MOSFET by shrinking the cell pitch.

1st Gen. Source Gate Q Source Metal SiO₂ n P base ate P base P base p () p^+ p⁺ n-drift layer n+ substrate 6 Drain

Cross section view of SiC-MOSFET

Technologies of Low R_{on}

- Narrow cell pitch
- Thin N+ substrate
- Trench gate structure





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On-state Voltage of Si IGBT / SiC MOSFET pcim

Compared to 1.2kV Si IGBT in 3-level NPC circuit,

- ◆ 2.3kV Si IGBT in 2-level circuit is 33% smaller.
- ◆ 2.3kV SiC-MOSFET in 2-level circuit is 37% smaller.





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On-state Voltage of Si FWD / SiC MOSFET

Compared to 1.2kV Si FWD in 3-level NPC circuit,

- ◆ 2.3kV Si FWD in 2-level circuit is 33% smaller.
- ◆ 2.3kV SiC-MOSFET (Body Diode) in 2-level circuit is 26% smaller.





Switching Waveforms of 2.3kV Si-IGBT pcim

- ◆ Larger turn-off and reverse recovery tail current at higher temperature
- Smaller di/dt at higher temperature
- ◆ Larger switching losses at the higher temperature

Turn-on waveform

Turn-off waveform

Reverse recovery waveform







Switching Waveforms of 2.3kV SiC-MOSFETpcim

- No tail current and small spike
- Smaller spike voltage at higher temperature







Power Dissipation Comparison



Conditions of I_0 =600Arms, V_{DC} =1500V, cos φ =1, λ =1.0, f_c =1 kHz, T_{vi} =150 degC.

2-level topology with 2.3kV Si IGBT and 3-level NPC topology with 1.2kV Si IGBT

2-level topology with 2.3kV SiC MOSFET and 3-level NPC topology with 1.2kV Si IGBT



The total power dissipation is almost the same.

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SiC device has better performance.



Benefits of 2.3kV device in 2-level topology

✓ Simplified circuits and drives, reduced dissipation losses

	3-level (Si)	2-level (Si)	2-level (SiC)
Number of devices	30 😕 (IGBT x12, FWD x18)	12 😕 (IGBT x6, FWDx6)	6 ☺ (MOSFET x6)
Footprint	100% 😕	33% 🙂	33% 🙂
Number of gate drivers	12 😕	6 🙂	6 🙂
Total loss	100% 😕	103% 😕	44% ⓒ
On-state loss	100% 😕	45% ©	38% 🙂
Switching loss	100% 😕	487% 😕	80% 😳







- Newly developed 2.3kV Si-IGBT and 2.3kV SiC-MOSFET with trench gate structure have been introduced.
- The 2.3kV devices are suitable for renewable energy applications with ~1500VDC bus voltage.
- The 2.3kV SiC-MOSFET has low power dissipation, and it can operate at higher switching frequency.
- The 2.3kV devices have the following benefits:
 - Simplified inverter design with a small number of gate drives
 - Low commutation inductance
 - Low on-state loss



